20 V, 3 A, Low V_{CE(sat)} **NPN Transistor**

ON Semiconductor's e²PowerEdge family of low V_{CE(sat)} transistors are miniature surface mount devices featuring ultra low saturation voltage (V_{CE(sat)}) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical application are DC–DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

| Rating | Symbol | Max | Unit | |
|--------------------------------|------------------|-----|------|--|
| Collector-Emitter Voltage | V _{CEO} | 20 | V | |
| Collector-Base Voltage | V _{CBO} | 40 | V | |
| Emitter-Base Voltage | V _{EBO} | 5.0 | V | |
| Collector Current – Continuous | I _C | 2.0 | Α | |
| Collector Current - Peak | I _{CM} | 3.0 | Α | |

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|--|--|----------------|-------|
| Total Device Dissipation T _A = 25°C | P _D (Note 1) | 460 | mW |
| Derate above 25°C | | 3.7 | mW/°C |
| Thermal Resistance, Junction-to-Ambient | , 00/1 | | °C/W |
| Total Device Dissipation T _A = 25°C | P _D (Note 2) | 780 | mW |
| Derate above 25°C | | 6.3 | mW/°C |
| Thermal Resistance, Junction-to-Ambient | R _{θJA} (Note 2) | 160 | °C/W |
| Thermal Resistance, Junction-to-Lead #1 | R _{θJL} (Note 1) R _{θJL} (Note 2) | 48 40 | °C/W |
| Total Device Dissipation (Single Pulse < 10 s) | P _{Dsingle} (Note 2) | 1.5 | W |
| Junction and Storage Temperature Range | T _J , T _{stg} | –55 to +150 | °C |

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

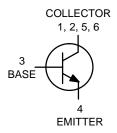
- FR-4 @ 100 mm2, 2 oz copper traces.
 FR-4 @ 500 mm2, 2 oz copper traces.



ON Semiconductor®

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20 VOLTS **3.0 AMPS** NPN LOW $V_{CE(sat)}$ TRANSISTOR EQUIVALENT $R_{DS(on)}$ 100 m Ω





CASE 318G TSOP-6 STYLE 6

DEVICE MARKING



VS0 = Specific Device Code

= Date Code = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|----------------|---------------------|-----------------------|
| NSS20201MR6T1G | TSOP-6 (Pb-Free) | 3000/Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NSS20201MR6T1G

查记了RIGAO2CHARACTERISTICS (本音25°C unless otherwise noted)

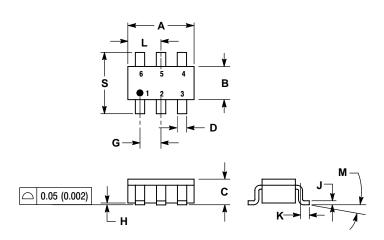
| Characteristic | Symbol | Min | Тур | Max | Unit |
|---|----------------------|-------------------|-------------|-------------------------|------|
| OFF CHARACTERISTICS | | | | | |
| Collector – Emitter Breakdown Voltage (I _C = 10 mA, I _B = 0) | V _{(BR)CEO} | 20 | _ | _ | V |
| Collector-Base Breakdown Voltage (I _C = 0.1 mA, I _E = 0) | V _{(BR)CBO} | 40 | _ | - | V |
| Emitter – Base Breakdown Voltage (I _E = 0.1 mA, I _C = 0) | V _{(BR)EBO} | 5.0 | - | - | V |
| Collector Cutoff Current (V _{CB} = 40 V, I _E = 0) | I _{CBO} | - | - | 0.1 | μΑ |
| Collector–Emitter Cutoff Current (V _{CES} = 20 V) | I _{CES} | - | _ | 0.1 | μΑ |
| Emitter Cutoff Current (V _{EB} = 5.0 V) | I _{EBO} | - | | 0.1 | μΑ |
| ON CHARACTERISTICS | | | | | |
| DC Current Gain (Note 3) (I _C = 1.0 mA, V _{CE} = 5.0 V) (I _C = 0.5 A, V _{CE} = 5.0 V) (I _C = 1.0 A, V _{CE} = 5.0 V) | h _{FE} | 300 300 200 | - - - | - - - | |
| Collector – Emitter Saturation Voltage (Note 3) ($I_C = 1.0 \text{ A}, I_B = 100 \text{ mA}$) ($I_C = 0.5 \text{ A}, I_B = 50 \text{ mA}$) ($I_C = 0.1 \text{ A}, I_B = 10 \text{ mA}$) | V _{CE(sat)} | - - - | - - - | 0.150 0.100 0.025 | V |
| Base – Emitter Saturation Voltage (Note 3) (I _C = 1.0 A, I _B = 0.1 A) | V _{BE(sat)} | - | - | 0.95 | V |
| Base – Emitter Turn–on Voltage (Note 3) (I _C = 1.0 A, V _{CE} = 2.0 V) | V _{BE(on)} | - | - | 0.90 | V |
| Cutoff Frequency ($I_C = 100 \text{ mA}$, $V_{CE} = 5.0 \text{ V}$, $f = 100 \text{ MHz}$ | f _T | 200 | _ | _ | MHz |
| Output Capacitance (f = 1.0 MHz) | C _{obo} | _ | _ | 15 | pF |

^{3.} Pulsed Condition: Pulse Width \leq 300 µsec, Duty Cycle \leq 2%.

查询"NSS20201MR6T1G-D"供应商

PACKAGE DIMENSIONS

TSOP-6 CASE 318G-02 **ISSUE N**



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

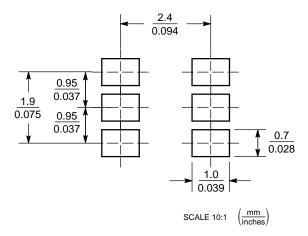
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS.
- OF BASE MATERIAL.
 DIMENSIONS A AND B DO NOT INCLUDE
 MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| | MILLIMETERS | | INC | HES |
|-----|-------------|-------|--------|--------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 2.90 | 3.10 | 0.1142 | 0.1220 |
| В | 1.30 | 1.70 | 0.0512 | 0.0669 |
| С | 0.90 | 1.10 | 0.0354 | 0.0433 |
| D | 0.25 | 0.50 | 0.0098 | 0.0197 |
| G | 0.85 | 1.05 | 0.0335 | 0.0413 |
| Н | 0.013 | 0.100 | 0.0005 | 0.0040 |
| J | 0.10 | 0.26 | 0.0040 | 0.0102 |
| K | 0.20 | 0.60 | 0.0079 | 0.0236 |
| L | 1.25 | 1.55 | 0.0493 | 0.0610 |
| М | 0 | 10 | 0 | 10 |
| S | 2.50 | 3.00 | 0.0985 | 0.1181 |

STYLE 6:

PIN 1. COLLECTOR
2. COLLECTOR
3. BASE
4. EMITTER
5. COLLECTOR
6. COLLECTOR

SOLDERING FOOTPRINT*



^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NSS20201MR6T1G

查询"NSS20201MR6T1G-D"供应商

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